2.5 V / 3.3 V ECL **Differential Receiver/Driver**

Description

The MC10/100LVEP16 is a world class differential receiver/driver. The device is functionally equivalent to the EL16, EP16 and LVEL16 devices. With output transition times significantly faster than the EL16 and LVEL16, the LVEP16 is ideally suited for interfacing with high frequency and low voltage (2.5 V) sources. Single-Ended CLK input operation is limited to a $V_{CC}\!\ge\!3.0~V$ in PECL mode, or $V_{EE}\!\le\!-3.0~V$ in NECL mode.

The V_{BB} pin, an internally generated Voltage supply, is available to this device only. For Single-Ended input conditions, the unused differential input is connected to VBB as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and $V_{\text{CC}}\,\text{via}$ a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series contains temperature compensation.

Features

- 240 ps Propagation Delay
- Maximum Frequency = > 4 GHz Typical
- PECL Mode Operating Range: V_{CC} = 2.375 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: $V_{CC} = 0 \text{ V}$ with $V_{EE} = -2.375 \text{ V}$ to -3.8 V
- V_{BB} Output
- Open Input Default State
- LVDS Input Compatible
- · These Devices are Pb-Free, Halogen Free and are RoHS Compliant



ON Semiconductor®

www.onsemi.com







SOIC-8 NB D SUFFIX

DT SUFFIX CASE 751-07 CASE 948R-02 CASE 506AA

MN SUFFIX

MARKING DIAGRAMS*













SOIC-8 NB

TSSOP-8

DFN8

H = MC10

A = Assembly Location L = Wafer Lot

K = MC1005Y = MC10

Y = Year

4L = MC100

W = Work Week

M = Date Code = Pb-Free Package (Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

^{*}For additional marking information, refer to Application Note AND8002/D.

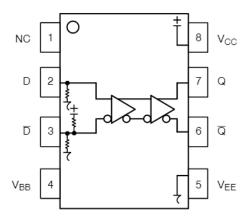


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
D*, \(\overline{D} **	ECL Data Inputs
Q, Q	ECL Data Outputs
V _{BB}	Ref. Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal con- duit. Electrically connect to the most neg- ative supply (GND) or leave unconnec- ted, floating open.

Table 2. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	37.5 kΩ
ESD Protection Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
SOIC-8 NB NB TSSOP-8 DFN8	Level 1 Level 3 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	167 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

^{1.} For additional information, see Application Note AND8003/D.

^{*} Pins will default LOW when left open. **Pins will default to $V_{\rm CC}/2$ when left open.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$\begin{array}{c} V_I \leq V_{CC} \\ V_I \geq V_{EE} \end{array}$	6 -6	V
I _{out}	Output Current	Continuous Surge		50 100	mA
I _{BB}	V _{BB} Sink/Source			±0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB SOIC-8 NB	190 130	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W
T _{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN8	35 to 40	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

^{1.} JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

Table 4. 10EP DC CHARACTERISTICS, PECL (V_{CC} = 2.5 V, V_{EE} = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	17	22	27	17	22	27	17	22	28	mA
V _{OH}	Output HIGH Voltage (Note 2)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V _{OL}	Output LOW Voltage (Note 2)	565	740	865	630	805	930	690	865	990	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Notes 3, 4)	1.2		2.5	1.2		2.5	1.2		2.5	٧
I _{IH}	Input HIGH Current			150			150			150	μА
I _{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{FF} can vary +0.125 V to -1.3 V.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.
- 3. Do not use V_{BB} at $V_{CC} < 3.0$ V. Single ended input CLK pin operation is limited to $V_{CC} \ge 3.0$ V in PECL mode.
- 4. VIHCMR min varies 1:1 with VEE, VIHCMR max varies 1:1 with VCC. The VIHCMR range is referenced to the most positive side of the differential input signal.

Table 5. 10EP DC CHARACTERISTICS, PECL (V_{CC} = 3.3 V, V_{EE} = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	17	22	27	17	22	27	17	22	28	mA
V _{OH}	Output HIGH Voltage (Note 2)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V _{OL}	Output LOW Voltage (Note 2)	1365	1540	1665	1430	1605	1730	1490	1665	1790	mV
V _{IH}	Input HIGH Voltage (Single Ended)	2090		2415	2155		2480	2215		2540	mV
V _{IL}	Input LOW Voltage (Single Ended)	1365		1690	1430		1755	1490		1815	mV
V _{BB}	Output Voltage Reference (Note 3)	1790	1890	1990	1855	1955	2055	1915	2015	2115	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	1.2		3.3	1.2		3.3	1.2		3.3	٧
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925 V to -0.5 V.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.
- Single ended input CLK pin operation is limited to V_{CC} ≥ 3.0 V in PECL mode.
 V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 6. 10EP DC CHARACTERISTICS, NECL ($V_{CC} = 0 \text{ V}$, $V_{EE} = -3.8 \text{ V}$ to -2.375 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	17	22	27	17	22	27	17	22	28	mA
VOH	Output HIGH Voltage (Note 2)	-1135	-1010	-885	-1070	-945	-820	-1010	-885	-760	mV
V _{OL}	Output LOW Voltage (Note 2)	-1935	-1760	-1635	-1870	-1695	-1570	-1810	-1635	-1510	mV
V _{IH}	Input HIGH Voltage (Single Ended)	-1210		-885	-1145		-820	-1085		-760	mV
V _{IL}	Input LOW Voltage (Single Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
V _{BB}	Output Voltage Reference (Note 3)	-1510	-1410	-1310	-1445	-1345	-1245	-1385	-1285	-1185	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	VEE	+1.2	0.0	VEE	+1.2	0.0	V _{EE}	+1.2	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μА
IIL	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC}.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.
- 3. Single ended input CLK pin operation is limited to $V_{EE} \le -3.0 \text{ V}$ in NECL mode.
- 4. VIHCMR min varies 1:1 with VEE, VIHCMR max varies 1:1 with VCC. The VIHCMR range is referenced to the most positive side of the differential input signal.

Table 7. 100EP DC CHARACTERISTICS, PECL (V_{CC} = 2.5 V, V_{EE} = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	19	24	29	22	28	34	24	30	36	mA
V _{OH}	Output HIGH Voltage (Note 2)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V _{OL}	Output LOW Voltage (Note 2)	555	730	900	555	730	900	555	730	900	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Notes 3, 4)	1.2		3.3	1.2		3.3	1.2		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μА
I _{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.125 V to -1.3 V.
- 2. All loading with 50 Ω to V_{CC} 2.0 V. 3. Do not use V_{BB} at V_{CC} <3.0 V. Single ended input CLK pin operation is limited to V_{CC} \geq 3.0 V in PECL mode.
- 4. VIHCMR min varies 1:1 with VEE, VIHCMR max varies 1:1 with VCC. The VIHCMR range is referenced to the most positive side of the differential input signal.

Table 8. 100EP DC CHARACTERISTICS, PECL (V_{CC} = 3.3 V, V_{EE} = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	19	24	29	22	28	34	24	30	36	mA
V _{OH}	Output HIGH Voltage (Note 2)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Output LOW Voltage (Note 2)	1355	1530	1700	1355	1530	1700	1355	1530	1700	mV
V _{IH}	Input HIGH Voltage (Single Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single Ended)	1355		1700	1355		1700	1355		1700	mV
V _{BB}	Output Voltage Reference (Note 3)	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	1.2		3.3	1.2		3.3	1.2		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μА
IIL	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925 V to -0.5 V.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.
- 3. Single ended input CLK pin operation is limited to $V_{CC} \ge 3.0 \text{ V}$ in PECL mode.
- V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 9. 100EP DC CHARACTERISTICS, NECL (V_{CC} = 0 V, V_{EE} = -3.8 V to -2.375 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	19	24	29	22	28	34	24	30	36	mA
V _{OH}	Output HIGH Voltage (Note 2)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V _{OL}	Output LOW Voltage (Note 2)	-1945	-1770	-1600	-1945	-1770	-1600	-1945	-1770	-1600	mV
V _{IH}	Input HIGH Voltage (Single Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single Ended)	-1945		-1600	-1945		-1600	-1945		-1600	mV
V _{BB}	Output Voltage Reference (Note 3)	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	VEE	+1.2	0.0	V _{EE}	+1.2	0.0	V _{EE}	+1.2	0.0	V
lін	Input HIGH Current			150			150			150	μА
I _{IL}	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC}.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.
- 3. Single ended input CLK pin operation is limited to $V_{EE} \le -3.0 \text{ V}$ in NECL mode.
- V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 10. AC CHARACTERISTICS ($V_{CC} = 0 \text{ V}; V_{EE} = -3.8 \text{ V} \text{ to } -2.375 \text{ V} \text{ or } V_{CC} = 2.375 \text{ V} \text{ to } 3.8 \text{ V}; V_{EE} = 0 \text{ V} \text{ (Note 1))}$

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (See Figure 2. F _{max} /JITTER)		> 4			> 4			> 4		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential	150	220	300	170	240	320	190	260	330	ps
tskew	Duty Cycle Skew (Note 2)		5.0	20		5.0	20		5.0	20	ps
UITTER	CLOCK Random Jitter (RMS) @ ≤ 1.0 GHz @ ≤ 1.5 GHz @ ≤ 2.0 GHz @ ≤ 2.5 GHz @ ≤ 3.0 GHz @ ≤ 3.5 GHz		0.134 0.077 0.115 0.117 0.122 0.123	0.2 0.2 0.2 0.2 0.2 0.2		0.147 0.104 0.141 0.132 0.143 0.145	0.3 0.3 0.3 0.3 0.3 0.3		0.166 0.145 0.153 0.156 0.177 0.202	0.3 0.3 0.3 0.3 0.3 0.3	ps
V _{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
t _r t _f	Output Rise/Fall Times Q, Q (20% – 80%)	70	120	170	80	130	180	100	150	200	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

^{1.} Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} – 2.0 V. 2. Skew is measured between outputs under identical transitions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

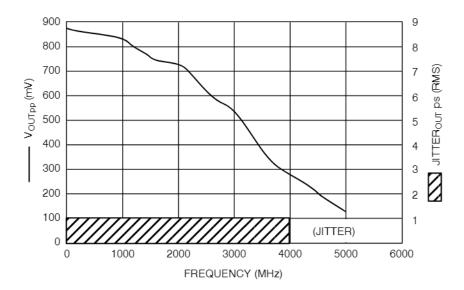


Figure 2. $F_{\text{max}}/Jitter$

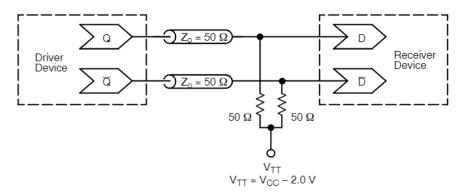


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10LVEP16DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
MC10LVEP16DR2G	SOIC-8 NB (Pb-Free)	2500 / Tape & Reel
MC10LVEP16DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
MC10LVEP16DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEP16DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
MC100LVEP16DR2G	SOIC-8 NB (Pb-Free)	2500 / Tape & Reel
MC100LVEP16DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
MC100LVEP16DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEP16MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

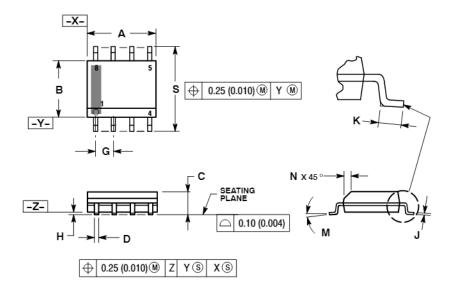
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB D SUFFIX CASE 751-07 ISSUE AK



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.
- PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR

 PROTRUSION. ALLOWABLE DAMBAR

 PROTRUSION SHALL BE 0.127 (0.005) TOTAL

 IN EXCESS OF THE D DIMENSION AT

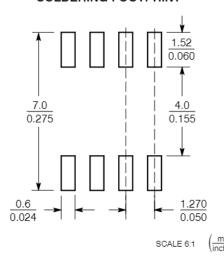
 MAXIMUM MATERIAL CONDITION.

 751-01 THRU 751-06 ARE OBSOLETE. NEW

 STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.05	0 BSC
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
s	5.80	6.20	0.228	0.244

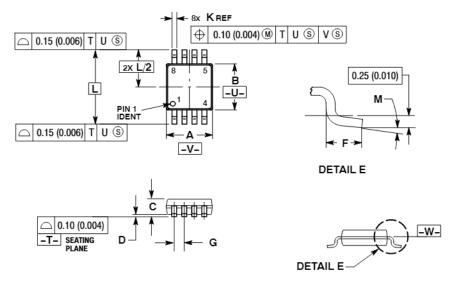
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX CASE 948R-02 ISSUE A



NOTES:

- DTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- EXCEED 0.25 (0.010) PER SIDE.

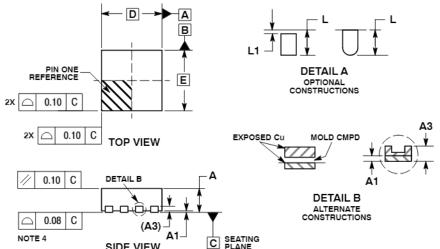
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
м	U.o.	6 0	0°	6°

PACKAGE DIMENSIONS

DFN8 2x2, 0.5 P MN SUFFIX CASE 506AA ISSUE F



SIDE VIEW

←D2→

BOTTOM VIEW

8x L

0.10 | C | A | B

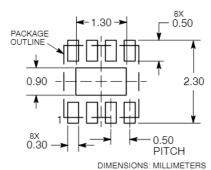
0.05 С NOTE 3

DETAIL Δ

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 . CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION & APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.20 MM FROM TERMINAL TIP COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.80	1.00			
Α1	0.00	0.05			
A 3	0.20 REF				
b	0.20	0.30			
D	2.00 BSC				
D2	1.10	1.30			
Е	2.00 BSC				
E2	0.70	0.90			
е	0.50 BSC				
K	0.30 REF				
L	0.25	0.35			
L1		0.10			

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries

Phone: 81-3-5817-1050

ON Semiconductor and 🕠 are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability. arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative